

TechConnect Ventures

Sprint Challenge Brief:

Innovations in fresh food packaging

BACKGROUND

On behalf of multiple international corporations, TechConnect Ventures is seeking innovations and emerging technologies from around the world describing new materials for use in fresh produce packaging applications. Currently, a significant amount of produce is wasted due to spoilage or early ripening. Extending produce shelf life has the potential to reduce food waste and improve the source-to-consumer value chain, passing significant cost savings on to consumer, retailers, and farmers. Submissions and novel concepts from individuals and organizations at all levels are strongly encouraged, including the academia, research, commercial and government sectors.

AREAS OF INTEREST

Our clients are broadly interested in any technologies that have the ability to impact the fresh produce / fresh food packaging sector. As such, TechConnect Ventures is calling for Entries describing any materials, products, processes, adjacent innovations or combinations thereof that can impact fresh food packaging. Relevant areas of interest include, but are not limited to, materials, designs or alternative approaches for:

- Packaging for ready-cut/ready-to-eat produce
- Packaging that can increase shelf-life by delaying ripening/aging
- Materials and designs to enhance physical protection or cushioning
- Solutions that enable gas exchange to slow produce respiration
- Solutions that manage or control microbial loads or enzymatic activity

BUSINESS OPPORTUNITY FOR SOLVERS

All complete and eligible Entries will be included in our exclusive Innovation Opportunity Report that will be presented to the innovation-seeking clients and partners. Solvers with well-matched capabilities may be contacted directly by consortium members to discuss potential partnership opportunities. Top-rated Entries may also be invited to register or participate in an upcoming TechConnect Ventures event or pitch program.

PARTICIPATION RULES & GUIDELINES

1. You must complete the provided Submission webform on the Sprint Submission page.
2. You are encouraged to submit a short presentation or pitch deck. A template is available on the Submission page.
3. **DO NOT INCLUDE ANY INFORMATION MARKED CONFIDENTIAL, PROPRIETARY, SENSITIVE OR CLASSIFIED. SUBMISSIONS MARKED AS SUCH WILL NOT BE SHARED WITH CLIENTS.**

Solvers should review the [Rules](#) and [Guidelines](#) provided on the Sprint page for full details about participation, including submission criteria, eligibility information, and more.

QUESTIONS? Contact Executive Director, Nick Kacsandi at info@techconnectventures.com